

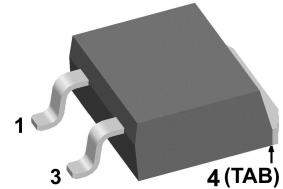
High Efficiency Thyristor

V_{RRM} = 1200 V
 I_{TAV} = 30 A
 V_T = 1,27 V

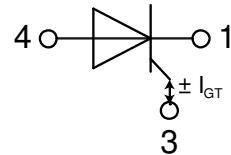
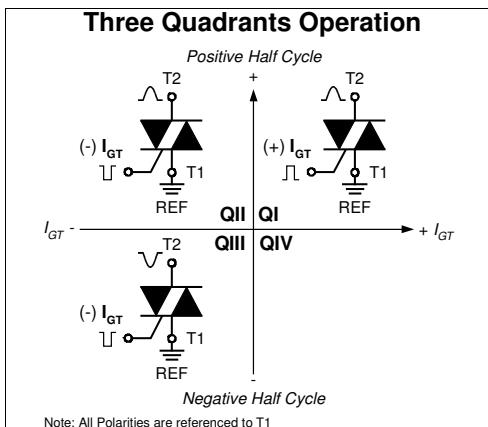
Two Quadrants Operation QI & QII
Single Thyristor with two gate polarities

Part number

CLA30E1200NPZ



Backside: anode



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Two gate current polarities usable
 - positive -> quadrant I
 - negative -> quadrant II
- Thyristor can be used as Triac
 - anti-parallel combination with AGT
 - Anode-Gated-Thyristor covers quadrant III
 - AGT-counterpart: CLB30I1200PZ

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-263 (D2Pak-HV)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms .Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments;

- the conclusion of quality agreements;

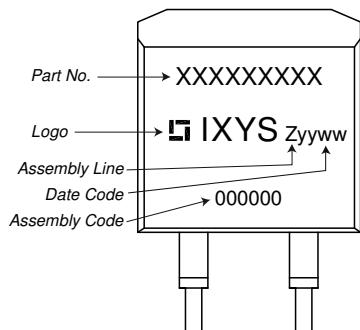
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

| Thyristor | | | Ratings | | | |
|-------------------|---|--|---|------|------------------------------|--------------------------------------|
| Symbol | Definition | Conditions | min. | typ. | max. | Unit |
| $V_{RSM/DSM}$ | max. non-repetitive reverse/forward blocking voltage | $T_{VJ} = 25^\circ C$ | | | 1300 | V |
| $V_{RRM/DRM}$ | max. repetitive reverse/forward blocking voltage | $T_{VJ} = 25^\circ C$ | | | 1200 | V |
| $I_{R/D}$ | reverse current, drain current | $V_{R/D} = 1200 V$ $V_{R/D} = 1200 V$ | $T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$ | | 10 2 | μA mA |
| V_T | forward voltage drop | $I_T = 30 A$ $I_T = 60 A$ $I_T = 30 A$ $I_T = 60 A$ | $T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$ | | 1,30 1,59 1,27 1,65 | V V |
| I_{TAV} | average forward current | $T_C = 115^\circ C$ | $T_{VJ} = 150^\circ C$ | | 30 | A |
| $I_{T(RMS)}$ | RMS forward current | 180° sine | | | 47 | A |
| V_{T0} r_T | threshold voltage slope resistance } for power loss calculation only | | $T_{VJ} = 150^\circ C$ | | 0,86 13,2 | V $m\Omega$ |
| R_{thJC} | thermal resistance junction to case | | | | 0,5 | K/W |
| R_{thCH} | thermal resistance case to heatsink | | | | 0,25 | K/W |
| P_{tot} | total power dissipation | | $T_C = 25^\circ C$ | | 250 | W |
| I_{TSM} | max. forward surge current | $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ | $T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 150^\circ C$ $V_R = 0 V$ | | 300 325 255 275 | A A |
| I^2t | value for fusing | $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ | $T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 150^\circ C$ $V_R = 0 V$ | | 450 440 325 315 | A^2s A^2s A^2s A^2s |
| C_J | junction capacitance | $V_R = 400 V$ $f = 1 \text{ MHz}$ | $T_{VJ} = 25^\circ C$ | | 13 | pF |
| P_{GM} | max. gate power dissipation | $t_p = 30 \mu s$ $t_p = 300 \mu s$ | $T_C = 150^\circ C$ | | 10 5 0,5 | W W W |
| P_{GAV} | average gate power dissipation | | | | | |
| $(di/dt)_{cr}$ | critical rate of rise of current | $T_{VJ} = 150^\circ C; f = 50 \text{ Hz}$ repetitive, $I_T = 90 A$ $t_p = 200 \mu s; di_G/dt = 0,3 A/\mu s;$ $I_G = 0,3 A; V = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 30 A$ | | | 150 | $A/\mu s$ |
| $(dv/dt)_{cr}$ | critical rate of rise of voltage | $V = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$; method 1 (linear voltage rise) | $T_{VJ} = 150^\circ C$ | | 500 | $V/\mu s$ |
| V_{GT} | gate trigger voltage | $V_D = 6 V$ | $T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$ | | 1,3 1,6 | V V |
| I_{GT} | gate trigger current | $V_D = 6 V$ | $T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$ | | ± 30 ± 50 | mA mA |
| V_{GD} | gate non-trigger voltage | $V_D = \frac{2}{3} V_{DRM}$ | $T_{VJ} = 150^\circ C$ | | 0,2 | V |
| I_{GD} | gate non-trigger current | | | | ± 1 | mA |
| I_L | latching current | $t_p = 10 \mu s$ $I_G = 0,3 A; di_G/dt = 0,3 A/\mu s$ | $T_{VJ} = 25^\circ C$ | | 90 | mA |
| I_H | holding current | $V_D = 6 V$ $R_{GK} = \infty$ | $T_{VJ} = 25^\circ C$ | | 60 | mA |
| t_{gd} | gate controlled delay time | $V_D = \frac{1}{2} V_{DRM}$ $I_G = 0,3 A; di_G/dt = 0,3 A/\mu s$ | $T_{VJ} = 25^\circ C$ | | 2 | μs |
| t_q | turn-off time | $V_R = 100 V; I_T = 30 A; V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ C$ $di/dt = 10 A/\mu s$ $dv/dt = 20 V/\mu s$ $t_p = 200 \mu s$ | | | 150 | μs |

Package TO-263 (D2Pak-HV)

| Symbol | Definition | Conditions | min. | typ. | max. | Unit |
|---------------|--|----------------------|------|------|------|------|
| I_{RMS} | RMS current | per terminal | | | 35 | A |
| T_{VJ} | virtual junction temperature | | -40 | | 150 | °C |
| T_{op} | operation temperature | | -40 | | 125 | °C |
| T_{stg} | storage temperature | | -40 | | 150 | °C |
| Weight | | | | 1,5 | | g |
| F_c | mounting force with clip | | 20 | | 60 | N |
| $d_{Spp/App}$ | creepage distance on surface / striking distance through air | terminal to terminal | 4,2 | | | mm |
| $d_{Spb/Apb}$ | | terminal to backside | 4,7 | | | mm |

Product Marking



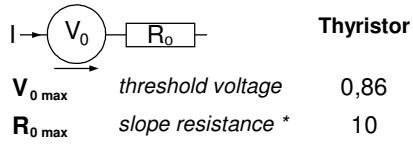
Part description

C = Thyristor (SCR)
 L = High Efficiency Thyristor
 A = (up to 1200V)
 30 = Current Rating [A]
 E = Single Thyristor
 1200 = Reverse Voltage [V]
 N = Three Quadrants operation: QI - QIII
 PZ = TO-263AB (D2Pak) (2HV)

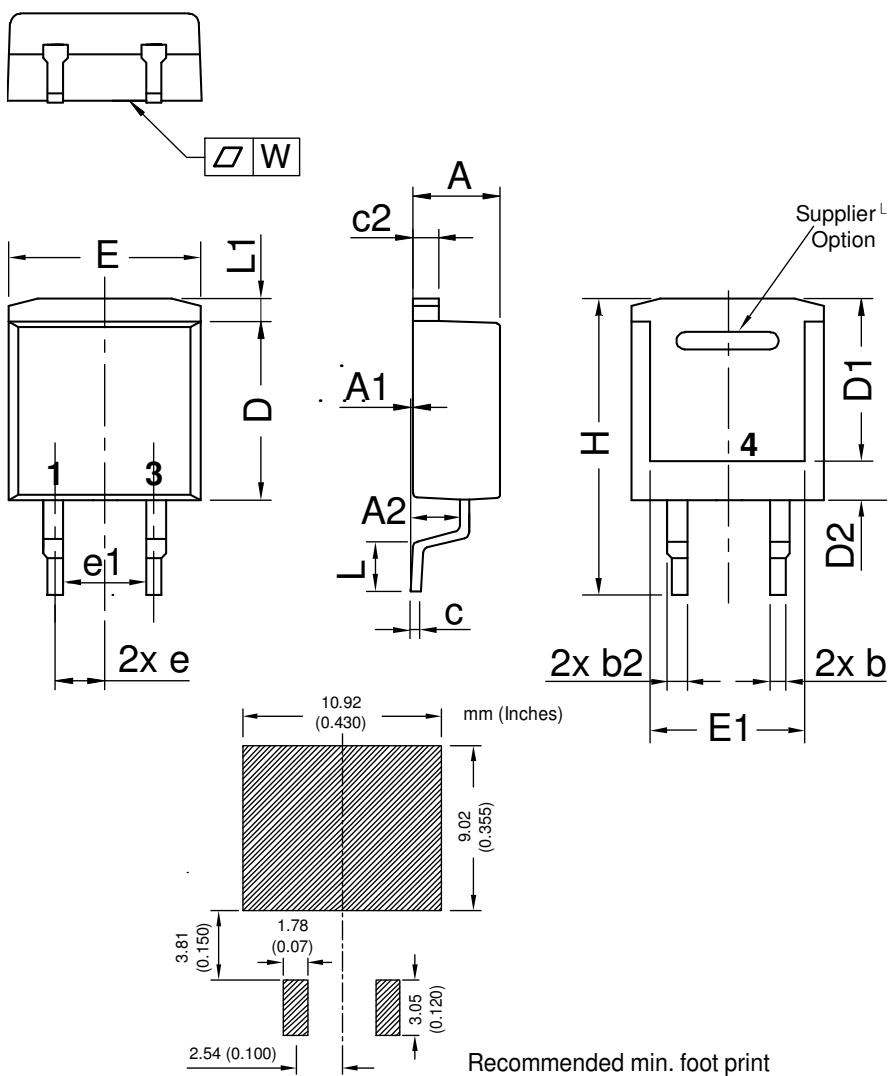
| Ordering | Ordering Number | Marking on Product | Delivery Mode | Quantity | Code No. |
|----------|-----------------|--------------------|---------------|----------|----------|
| Standard | CLA30E1200NPZ | CLA30E1200NPZ | Tape & Reel | 800 | 516330 |

Equivalent Circuits for Simulation

* on die level

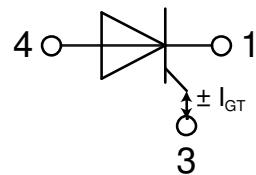
 $T_{VJ} = 150 \text{ }^{\circ}\text{C}$ 

Outlines TO-263 (D2Pak-HV)



| Dim. | Millimeter | | Inches | |
|------|------------|-------|------------|-------------|
| | min | max | min | max |
| A | 4.06 | 4.83 | 0.160 | 0.190 |
| A1 | typ. 0.10 | | typ. 0.004 | |
| A2 | 2.41 | | 0.095 | |
| b | 0.51 | 0.99 | 0.020 | 0.039 |
| b2 | 1.14 | 1.40 | 0.045 | 0.055 |
| c | 0.40 | 0.74 | 0.016 | 0.029 |
| c2 | 1.14 | 1.40 | 0.045 | 0.055 |
| D | 8.38 | 9.40 | 0.330 | 0.370 |
| D1 | 8.00 | 8.89 | 0.315 | 0.350 |
| D2 | 2.3 | | 0.091 | |
| E | 9.65 | 10.41 | 0.380 | 0.410 |
| E1 | 6.22 | 8.50 | 0.245 | 0.335 |
| e | 2,54 BSC | | 0,100 BSC | |
| e1 | 4.28 | | 0.169 | |
| H | 14.61 | 15.88 | 0.575 | 0.625 |
| L | 1.78 | 2.79 | 0.070 | 0.110 |
| L1 | 1.02 | 1.68 | 0.040 | 0.066 |
| W | typ. 0.02 | | 0.040 | typ. 0.0008 |
| | | | | 0.002 |

All dimensions conform with
and/or within JEDEC standard.



Thyristor

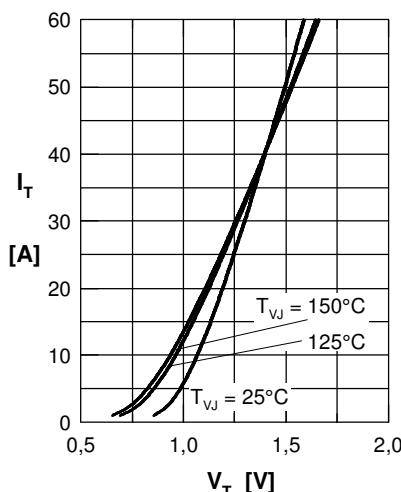


Fig. 1 Forward characteristics

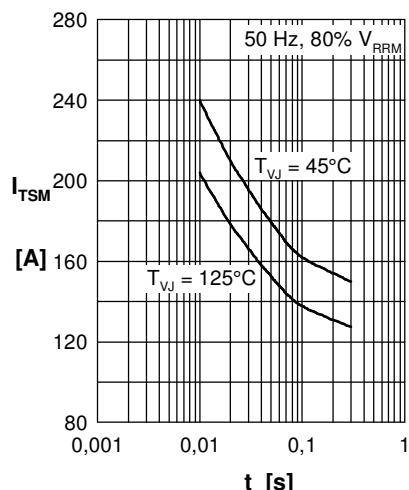
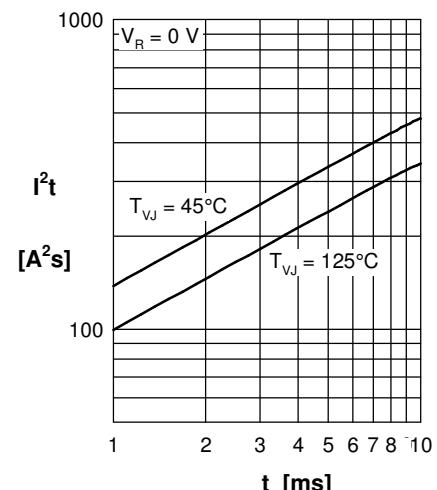
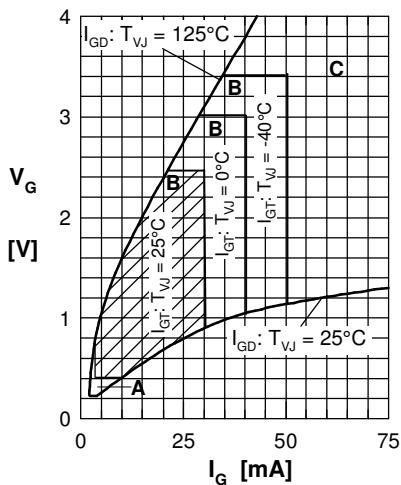
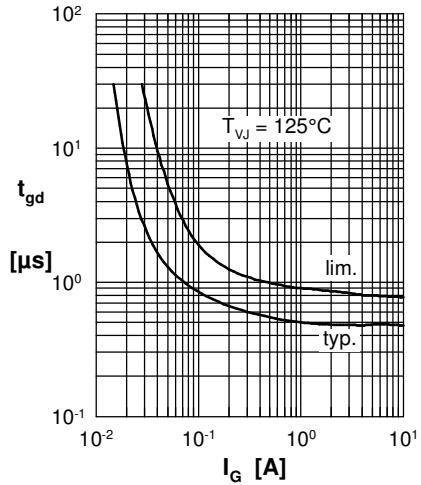
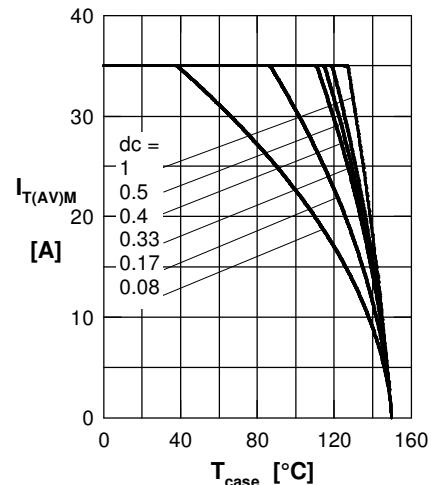
Fig. 2 Surge overload current
 I_{TSM} : crest value, t : durationFig. 3 I^2t versus time (1-10 s)Fig. 4 Gate voltage & gate current
Triggering: A = no; B = possible; C = safeFig. 5 Gate controlled delay time t_{gd} 

Fig. 6 Max. forward current at case temperature

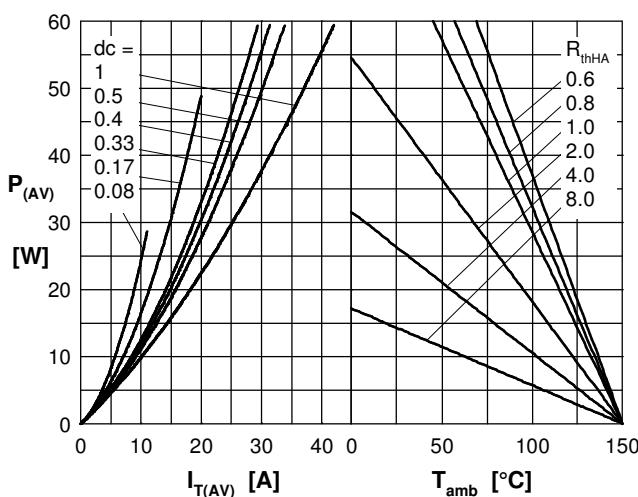
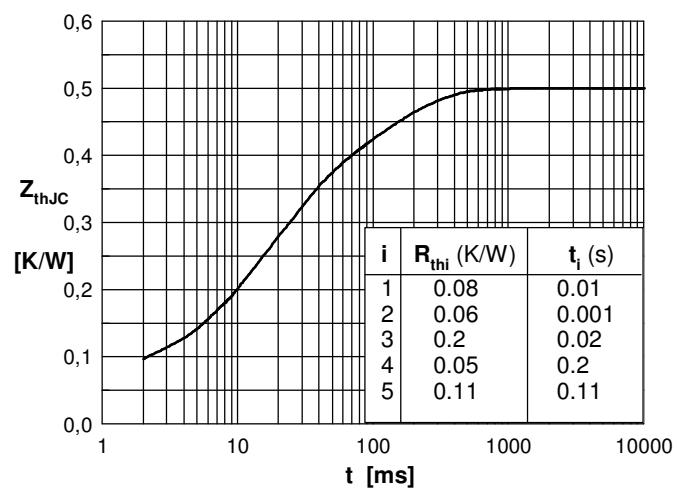
Fig. 7a Power dissipation versus direct output current
Fig. 7b and ambient temperature

Fig. 7 Transient thermal impedance junction to case